

Patent Abstracts of Japan

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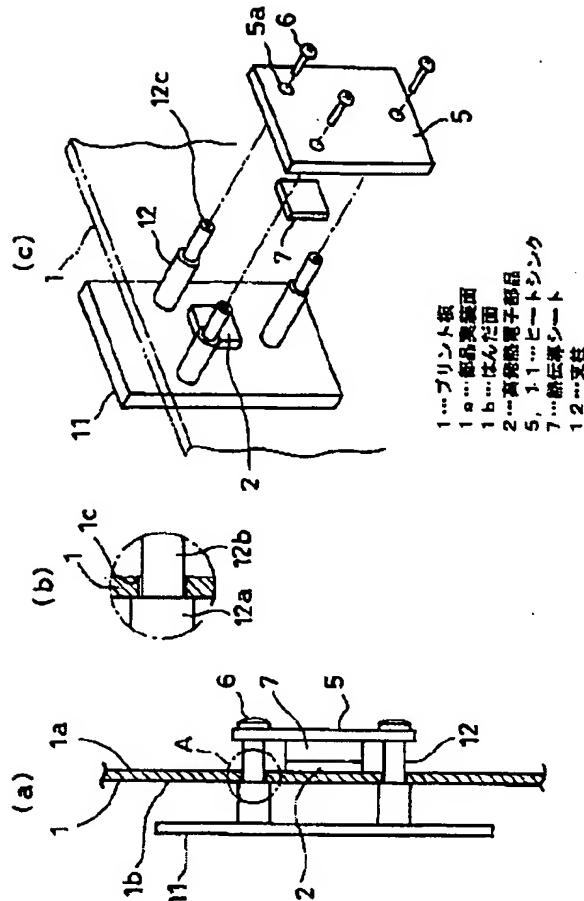
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H05K 1/02

TITLE : COOLING STRUCTURE FOR
ELECTRONIC COMPONENT



ABSTRACT : PROBLEM TO BE SOLVED: To reduce a limit in a component mounting height and to enhance a cooling effect.

SOLUTION: A high heating electronic component 2 is mounted on the component mounting surface 1a of a printed board 1, a first heat sink 5 is connected to the component 2 via a heat conductive sheet 7, a post 12 stood on a second heat sink 11 is arranged on the soldering surface 1b side of the board 1, and the sink 5 is mounted at the post 12 at the surface 1a side of the board 1.

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